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7c7a807c3a.rarIn industry, environments are required where high stresses such as mechanical and thermal stresses exist, and in addition, various gases are also generated in such environments. Therefore, in these environments, various structures have been developed which are capable of enduring the high stresses and the gas environment. For example, semiconductor wafers are used in the formation of integrated circuits, and these semiconductor wafers are manufactured with a high precision and are characterized by low mechanical strength and high thermal conductivity. Therefore, these semiconductor wafers are generally not mechanically and thermally durable enough to endure the environmental stresses. The above stresses can be divided into two categories. The first category is a mechanical stress such as a shearing stress in a surface direction of the semiconductor wafer.

This mechanical stress generates an internal stress in the semiconductor wafer in the wafer surface direction. The second category is a thermal stress. This thermal stress generates a thermal stress in the wafer. The thermal stress has two types of modes. One of the two types is a compressive stress, which is generated on the surface of the wafer due to temperature elevation of the semiconductor wafer. The other one is a tensile stress, which is generated on the surface of the wafer due to temperature reduction of the semiconductor wafer. Therefore, the thermal stresses generated on the surface of the wafer can be divided into a compressive stress mode and a tensile stress mode. The semiconductor wafer subjected to these stresses has a lower strength and lower reliability than a bulk-type semiconductor substrate, and therefore, the semiconductor wafer tends to break

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